

IN THE CLAIMS

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1. (Previously amended) A method of manufacturing a mini-card with a semiconductor memory device comprising the steps of:

providing an array of substrates including a plurality of individual substrates connected together;

mounting a semiconductor memory device on each of the individual substrates;

covering the individual substrates with respective cases; and

dividing, after the step of covering is completed, the substrate array to provide encased individual substrates each completing the mini-card having the semiconductor memory device embedded therein.

2. (Original) The method of manufacturing a mini-card with a semiconductor memory device according to claim 1, wherein, during the covering step, each substrate is sandwiched between top and bottom case segments.

3. (Original) The method of manufacturing a mini-card with a semiconductor memory device according to claim 1, wherein, during the covering step, each substrate is molded into case.

4. (Currently amended) A mini-card with a semiconductor memory device is characterized in that the mini-card is manufactured by a method comprising the steps of:

providing an array of substrates including a plurality of individual substrates connected together;

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mounting a semiconductor memory device on each of the individual substrates;  
covering the individual substrates with respective cases; and  
dividing, after the step of covering is completed, the substrate array to provide  
encased individual substrates each completing the mini-card having the semiconductor  
memory device embedded therein.

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5. (Cancelled)